

UFII Simple & Powerful IMPLANT



(A) + (B)

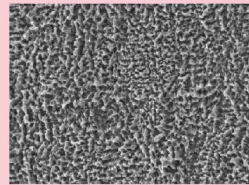
Dual Morse Tapered Connection (11 Morse)

The fixture & abutment interface ensures hermetic sealing. This distributes the load to fixture evenly. Therefore, it minimizes bone loss.

Open Thread

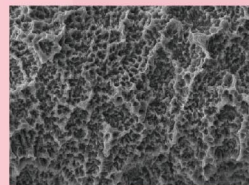
Fixture placement with minimum resistance. Possible to place deeper without drilling.

Platform Switching



Minimize Peri-Implantitis

Upper Ra: 0.5-1.0 μm
Less friction around cortical bone promotes less bone loss.

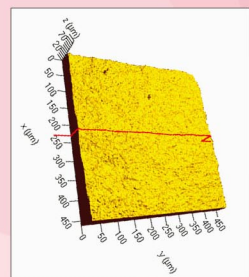


Stimulate Osseointegration

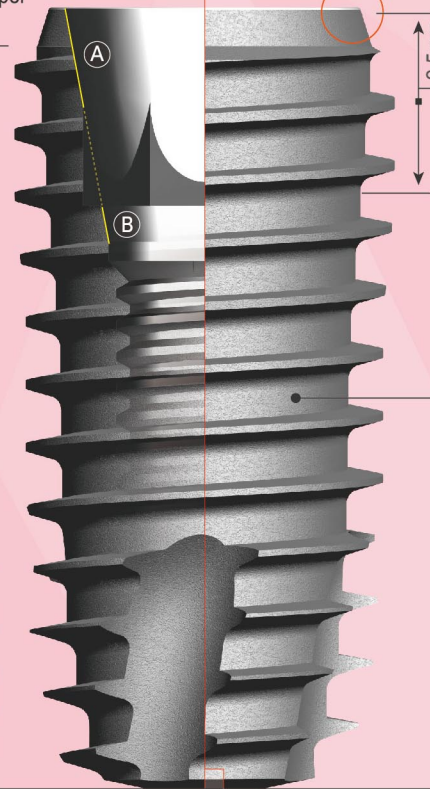
Body Ra: 2.0-2.5 μm
with ideal Ra 2.0~2.5 μm promotes not only rapid osseointegration but also long-term stability.

Excellent Quality Control

Perfect cleansing processes guarantee high safety.



- Ra_x: 2.212 ± 0.409 μm
- Ra_y: 2.210 ± 0.325 μm
- Sdr: 70.671 ± 2.900%
- Sa : 2.493 ± 0.129 μm



Upper Thread
Taper thread, initial fixation

Straight Body
Decrement of bone damage

Taper Body
15° Taper guide gradually

Apex Round Design



Cutting edge

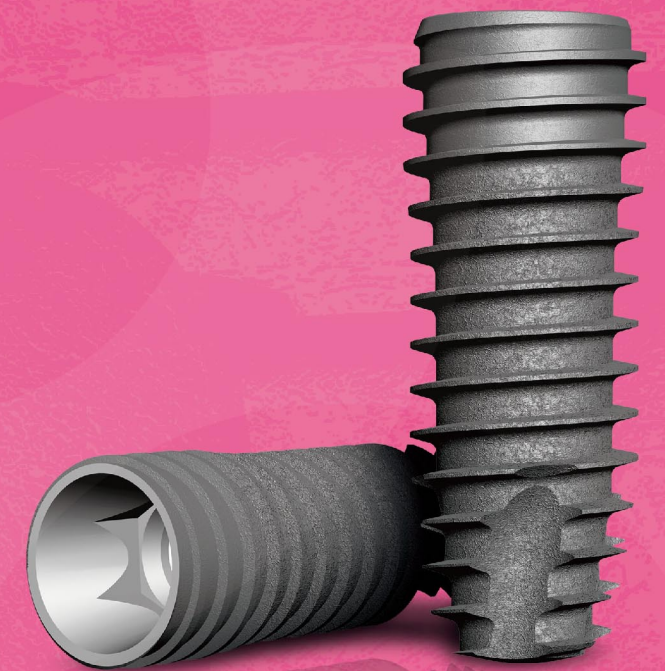
Maximize the efficiency of self-tapping with a sharp edge.

UFII HSA

[衛署醫器輸字第026862號] Hybrid SLA



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DIO IMPLANT
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